

CD54HC14, CD74HC14, CD54HCT14, CD74HCT14

High-Speed CMOS Logic Hex Inverting Schmitt Trigger

Features

- Unlimited Input Rise and Fall Times
- Exceptionally High Noise Immunity
- Fanout (Over Temperature Range)
 - Standard Outputs 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5V$
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility, $V_{IL} = 0.8V$ (Max), $V_{IH} = 2V$ (Min)
 - CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL} , V_{OH}

Description

The 'HC14 and 'HCT14 each contain six inverting Schmitt triggers in one package.

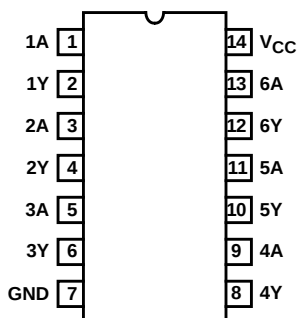
Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC14F3A	-55 to 125	14 Ld Cerdip
CD54HCT14F3A	-55 to 125	14 Ld Cerdip
CD74HC14E	-55 to 125	14 Ld PDIP
CD74HC14M	-55 to 125	14 Ld SOIC
CD74HC14MT	-55 to 125	14 Ld SOIC
CD74HC14M96	-55 to 125	14 Ld SOIC
CD74HC14PW	-55 to 125	14 Ld TSSOP
CD74HC14PWR	-55 to 125	14 Ld TSSOP
CD74HCT14E	-55 to 125	14 Ld PDIP
CD74HCT14M	-55 to 125	14 Ld SOIC
CD74HCT14MT	-55 to 125	14 Ld SOIC
CD74HCT14M96	-55 to 125	14 Ld SOIC
CD74HCT14PW	-55 to 125	14 Ld TSSOP
CD74HCT14PWR	-55 to 125	14 Ld TSSOP

NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel. The suffix T denotes a small-quantity reel of 250.

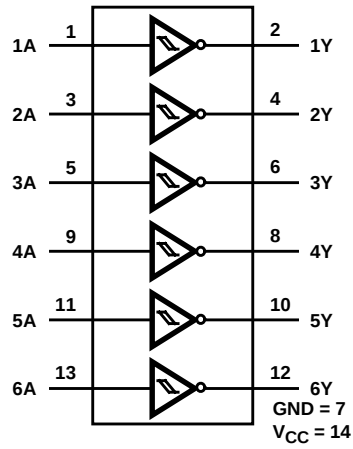
Pinout

CD54HC14, CD54HCT14
(CERDIP)
CD74HC14, CD74HCT14
(PDIP, SOIC, TSSOP)
TOP VIEW



CD54HC14, CD74HC14, CD54HCT14, CD74HCT14

Functional Diagram



TRUTH TABLE

INPUT (A)	OUTPUT (Y)
L	H
H	L

H= High Level
L= Low Level

Logic Diagram

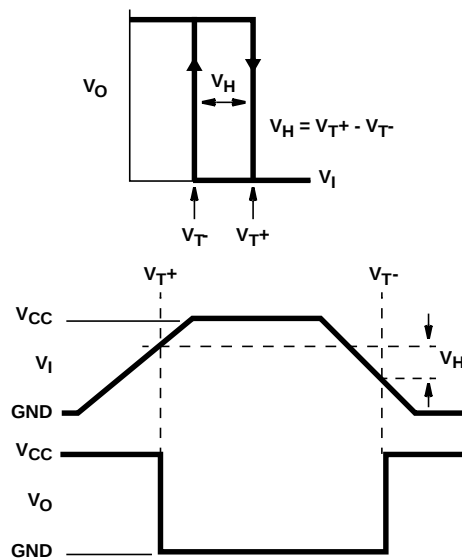
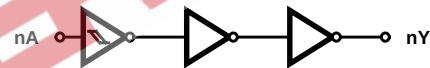


FIGURE 3. HYSTERESIS DEFINITION, CHARACTERISTIC, AND TEST SETUP

CD54HC14, CD74HC14, CD54HCT, CD74HCT14

Absolute Maximum Ratings

DC Supply Voltage, V_{CC}	-0.5V to 7V
DC Input Diode Current, I_{IK}	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Diode Current, I_{OK}	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$	$\pm 20mA$
DC Drain Current, per Output, I_O	
For $-0.5V < V_O < V_{CC} + 0.5V$	$\pm 25mA$
DC Output Source or Sink Current per Output Pin, I_O	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$	$\pm 25mA$
DC V_{CC} or Ground Current, I_{CC}	$\pm 50mA$

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} ($^{\circ}C/W$)
E (PDIP) Package	80
M (SOIC) Package	86
PW (TSSOP) Package	113
Maximum Junction Temperature (Hermetic Package or Die)	175 $^{\circ}C$
Maximum Junction Temperature (Plastic Package)	150 $^{\circ}C$
Maximum Storage Temperature Range	-65 $^{\circ}C$ to 150 $^{\circ}C$
Maximum Lead Temperature (Soldering 10s)	300 $^{\circ}C$
(SOIC - Lead Tips Only)	

Operating Conditions

Temperature Range, T_A	-55 $^{\circ}C$ to 125 $^{\circ}C$
Supply Voltage Range, V_{CC}	
HC Types	.2V to 6V
HCT Types	.4.5V to 5.5V
DC Input or Output Voltage, V_I , V_O	0V to V_{CC}

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V _{CC} (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
		V _I (V)	I _O (mA)		MIN	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
Input Switch Points	V _{T+}	-	-	2	0.7	1.5	0.7	1.5	0.7	1.5	V
				4.5	1.7	3.15	1.7	3.15	1.7	3.15	V
				6	2.1	4.2	2.1	4.2	2.1	4.2	V
	V _{T-}	-	-	2	0.3	1.0	0.3	1.0	0.3	1.0	V
				4.5	0.9	2.2	0.9	2.2	0.9	2.2	V
				6	1.2	3.0	1.2	3.0	1.2	3.0	V
	V _H	-	-	2	0.2	1.0	0.2	1.0	0.2	1.0	V
				4.5	0.4	1.4	0.4	1.4	0.4	1.4	V
				6	0.6	1.6	0.6	1.6	0.6	1.6	V
High Level Output Voltage CMOS Loads	V _{OH}	V _{T-} or V _{T+}	-0.02	2	1.9	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads			-	-	-	-	-	-	-	-	V
			-4	4.5	3.98	-	3.84	-	3.7	-	V
			-5.2	6	5.48	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	2	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			-	-	-	-	-	-	-	-	V
			4	4.5	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	0.26	-	0.33	-	0.4	V

CD54HC14, CD74HC14, CD54HCT14, CD74HCT14

DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V _{CC} (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
		V _I (V)	I _O (mA)		MIN	MAX	MIN	MAX	MIN	MAX	
Input Leakage Current	I _I	V _{CC} or GND	-	6	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I _{CC}	V _{CC} or GND	0	6	-	2	-	20	-	40	μA
HCT TYPES											
Input Switch Points	V _{T+}	-	-	4.5	1.2	1.9	1.2	1.9	1.2	1.9	V
				5.5	1.4	2.1	1.4	2.1	1.4	2.1	V
	V _T			4.5	0.5	1.2	0.5	1.2	0.5	1.2	V
				5.5	0.6	1.4	0.6	1.4	0.6	1.4	V
	V _H			4.5	0.4	1.4	0.4	1.4	0.4	1.4	V
				5.5	0.4	1.5	0.4	1.5	0.4	1.5	V
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	-0.02	4.5	4.4	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	4.5	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I _I	V _{CC} and GND	-	5.5	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I _{CC}	V _{CC} or GND	0	5.5	-	2	-	20	-	40	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI _{CC} (Note 2)	V _{CC} - 2.1	-	4.5 to 5.5	-	360	-	450	-	490	μA

NOTE:

- For dual-supply systems theoretical worst case ($V_I = 2.4V$, $V_{CC} = 5.5V$) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
nA	0.6

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Specifications table, e.g., 360 μA max at 25°C.

Switching Specifications Input $t_r, t_f = 6\text{ns}$

PARAMETER	SYMBOL	TEST CONDITIONS	V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
Propagation Delay, A to Y	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	135	-	170	-	205	ns
		C _L = 50pF	4.5	-	-	27	-	34	-	41	ns
		C _L = 15pF	5	-	11	-	-	-	-	-	ns
		C _L = 50pF	6	-	-	23	-	29	-	35	ns
Output Transition Times	t _{TLH} , t _{THL}	C _L = 50pF	2	-	-	75	-	95	18	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Input Capacitance	C _I	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C _{PD}	-	5	-	20	-	-	-	-	-	pF
HCT TYPES											
Propagation Delay, A to Y	t _{PLH} , t _{PHL}	C _L = 50pF	4.5	-	-	38	-	48	-	57	ns
		C _L = 15pF	5	-	16	-	-	-	-	-	ns
Output Transition Times	t _{TLH} , t _{THL}	C _L = 50pF	4.5	-	-	15	-	19	-	22	ns
Input Capacitance	C _I	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C _{PD}	-	5	-	20	-	-	-	-	-	pF

NOTES:

- C_{PD} is used to determine the dynamic power consumption, per inverter.
- $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$ where f_i = input frequency, C_L = output load capacitance, V_{CC} = supply voltage.

Test Circuits and Waveforms

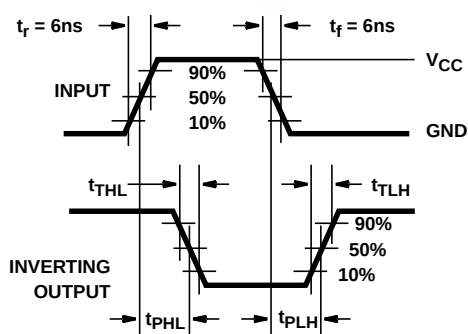


FIGURE 4. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

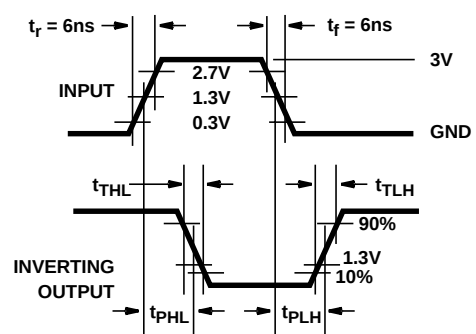


FIGURE 5. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD54HC14F	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
CD54HC14F3A	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
CD54HCT14F	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
CD54HCT14F3A	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
CD74HC14E	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74HC14M	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74HC14M96	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74HC14MT	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74HC14PW	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD74HC14PWR	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD74HCT14E	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74HCT14M	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74HCT14M96	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74HCT14MT	ACTIVE	SOIC	D	14	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74HCT14PW	ACTIVE	TSSOP	PW	14	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD74HCT14PWR	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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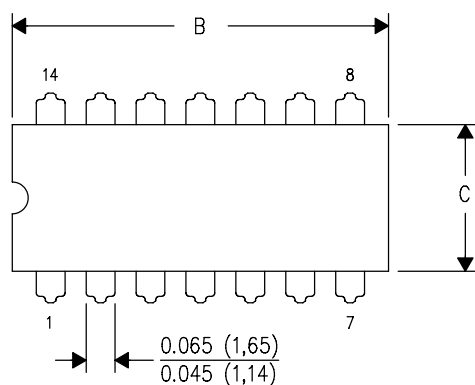
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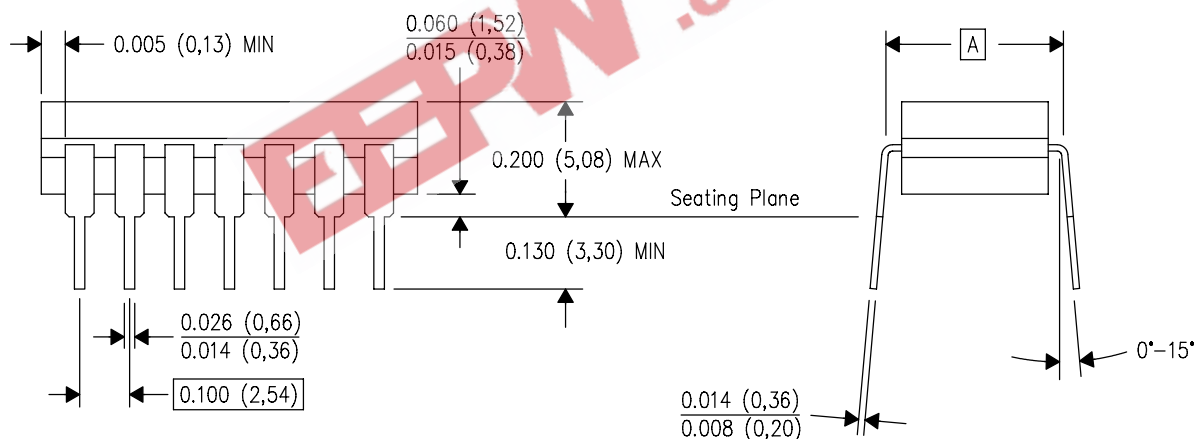
J (R—GDIP—T**)

14 LEADS SHOWN

CERAMIC DUAL IN—LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



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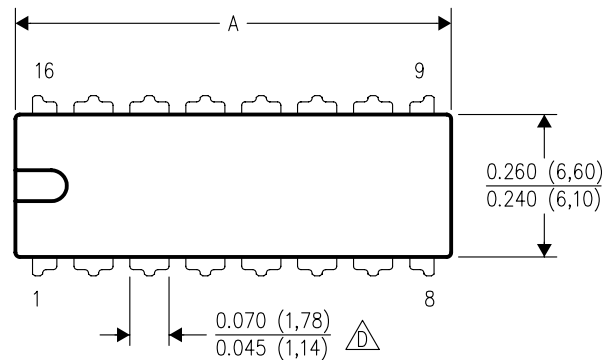
- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1—T14, GDIP1—T16, GDIP1—T18 and GDIP1—T20.

MECHANICAL DATA

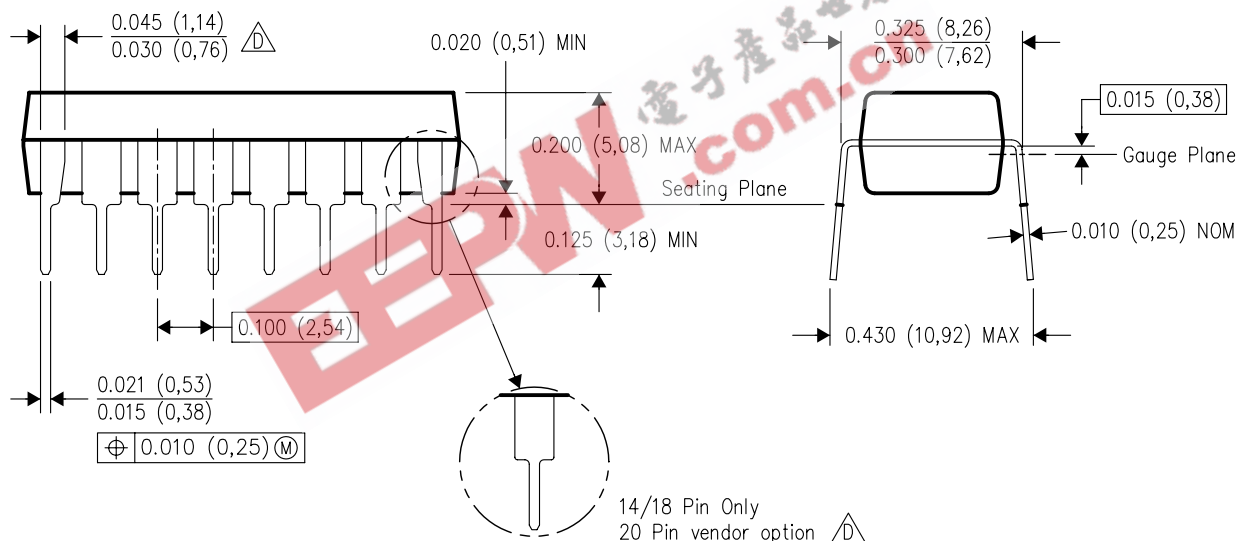
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



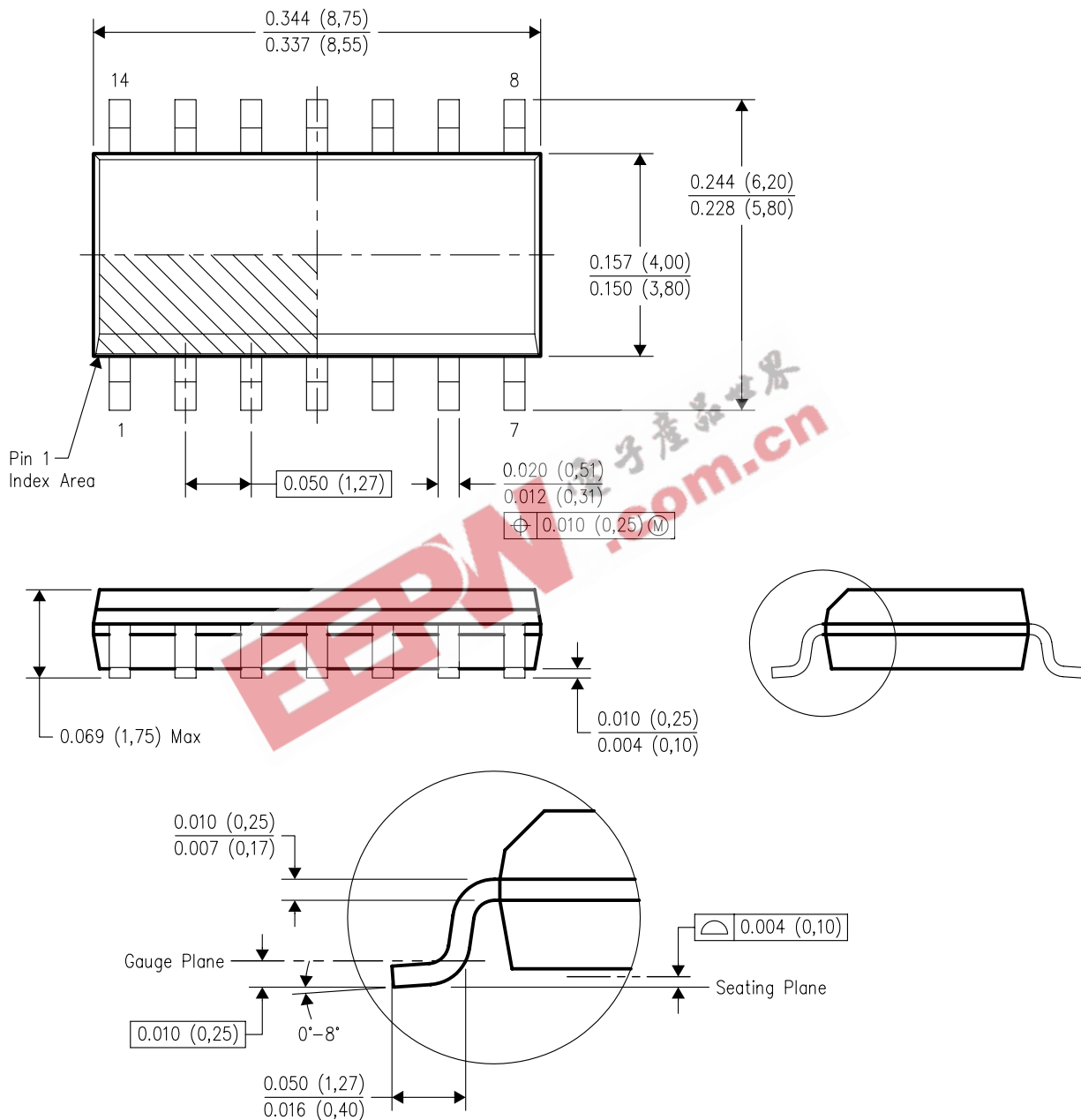
4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-3/F 07/2004

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-012 variation AB.

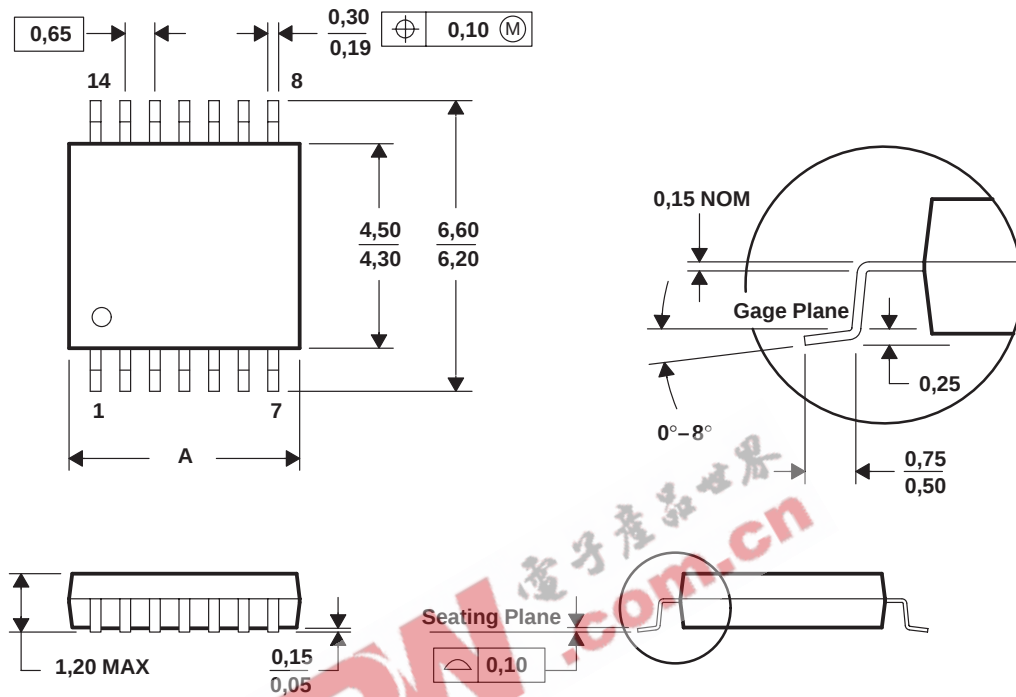
MECHANICAL DATA

MTSS001C – JANUARY 1995 – REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



	PINS **	8	14	16	20	24	28
DIM							
A MAX		3,10	5,10	5,10	6,60	7,90	9,80
A MIN		2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265